

PRODUCT NUMBER DESCRIPTION :

58102 - X XX - XX - XX X XX

PLATING

S = 0.38µm GOLD
ON CONTACT AREA
3.81µm TIN/LEAD
ON TAIL

G = 0.76µm GOLD
ON CONTACT AREA
3.81µm TIN/LEAD
ON TAIL

F = 0.20µm GOLD
ON CONTACT AREA
3.81µm TIN/LEAD
ON TAIL

LF = ROHS COMPLIANT (SEE NOTE 10)
BLANK = CONTAINS LEAD

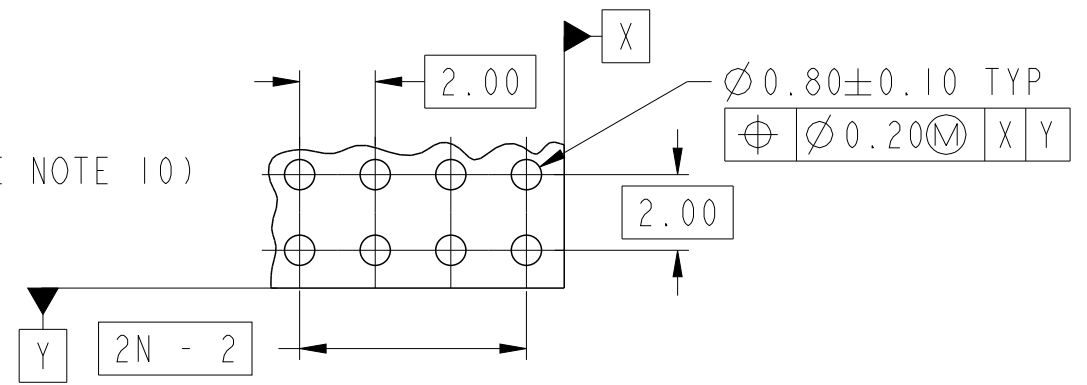
RETENTION
R: RETENTIVE LEG
NOTES 6,7

POLARIZATION
NOTE 7

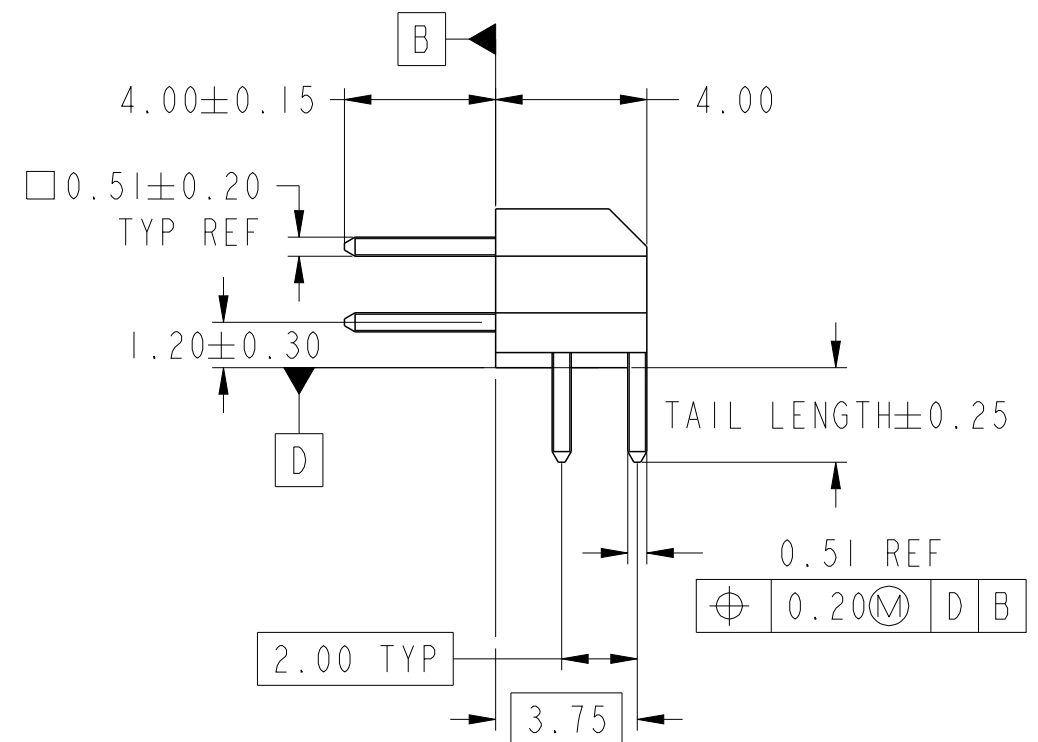
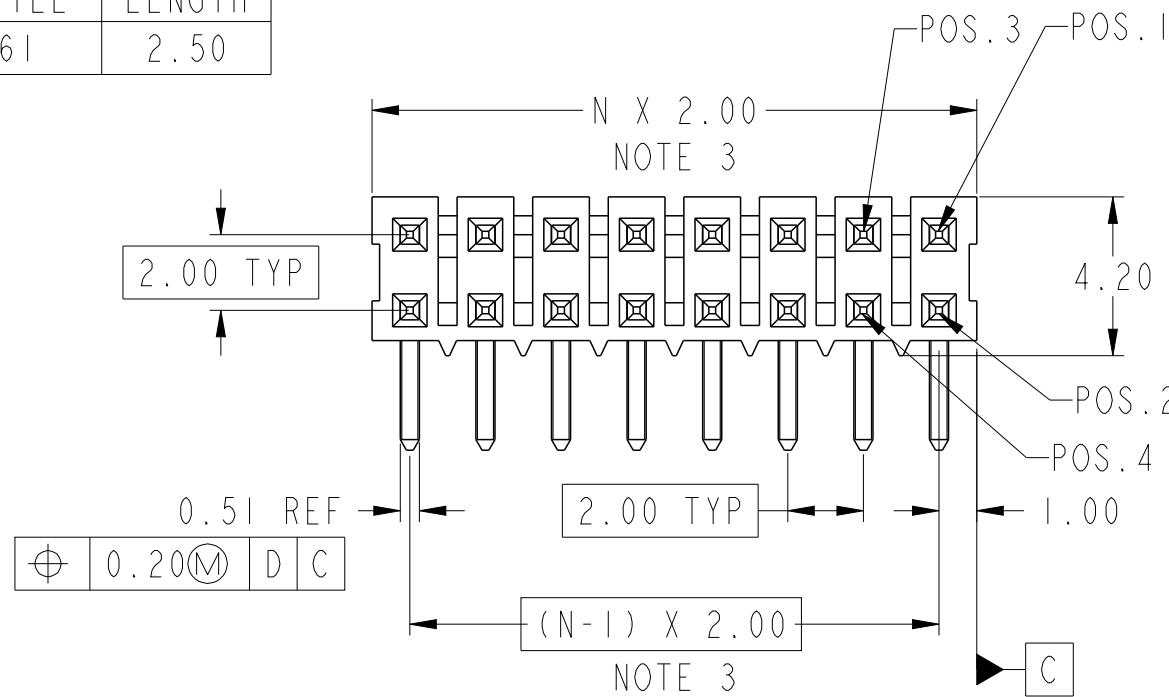
PACKAGING: = POLY BAGS
(NOTE 5) U = TUBES

POSITIONS PER ROW = "N"
(02 TO 25)

PIN STYLE	TAIL LENGTH
61	2.50



(RECOMMENDED HOLE PATTERN)
SCALE 5:1



0.51 REF	0.20 M	D	C
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0.51 REF	0.20 M	D	B
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spec ref	-	dr	Andrew Yong	2010/10/29	projection	MM	size	A3	scale	5:1			
tolerance std	ISO 406 ISO 1101	eng	Yuan-Yuan Bao	2022/03/08		← →	ecn no	ELX-N-44066-1					
	TOLERANCES UNLESS OTHERWISE SPECIFIED	chr	-	appr			Tim Yao	2022/03/09	product family	-	rel level	Released	
surface	linear	0.X	±0.5		2.0MM UNSHROUDED HEADER RIGHT ANGLE THRU-HOLE	dwg no 58102	rev H	ISO 1302					
	angular	0°	±3°					amphenol-icc.com	cat. no.	-	Product - Customer Drw	sheet 1 of 2	

NOTES:

- ① MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
- ② MATERIAL TERMINAL: COPPER ALLOY
- ③ TO DETERMINE DIMENSIONS:
N=NUMBER OF POSITIONS PER ROW
EX.: 10 POS., N x 2.00 = 20.00 TOTAL POSITIONS
- 4. 0.9kg MIN. PIN RETENTION IN EITHER DIRECTION.
- 5. PACKAGING;
(A) STANDARD PACKAGING: IN POLY BAGS.
(B) SPECIAL PACKAGING: IN TUBE.
FOR ALL SPECIAL PACKAGING, FCI MUST BE CONTACTED FOR AVAILABILITY IN SIZE REQUESTED.
- ⑥ RETENTION LEG:
2.3kg MAX INSERTION FORCE AND 1 kg MIN RETENTION FORCE PER RETENTIVE PIN USING 1.57 THICK CIRCUIT BOARD AND RECOMMENDED HOLE PATTERN. RETENTIVE LOCATION AT THE DISCRETION OF THE MANUFACTURER. RETENTION IS TWO PINS PER PART ADJACENT TO ONE ANOTHER.
- ⑦ FOR POLARIZATION, SPECIFY POSITION NUMBER, (i.e.: POS.3 = 03) TO OMIT PIN. OMIT FROM PRODUCT NUMBER IF FEATURE IS NOT APPLICABLE.
- 8. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- 9. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- ⑩ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.



dr	Andrew Yong	2010/10/29	projection 	MM ←————→	size	A3	scale	10:1
eng	Yuan-Yuan Bao	2022/03/08			ecn no	ELX-N-44066-1		
chr	-	-	product family	-	rel level	Released		
appr	Tim Yao	2022/03/09	Amphenol FCI		2.0MM UNSHROUDED HEADER	dwg no	58102	
					RIGHT ANGLE THRU-HOLE	rev	H	
amphenol-icc.com			cat. no.	-	Product - Customer Drw		sheet 2 of 2	